



CP 2827 B
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IR-1881 (2-2532) 10/23/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Bharat SHIVKUMAR et al.

Date: October 11, 2002

Serial No.: 09/812,027

Group Art Unit: 2827

Filed: March 19, 2001

Examiner: J. Mitchell

For: SEMICONDUCTOR MULTICHIP MODULE PACKAGE WITH IMPROVED
THERMAL PERFORMANCE; REDUCED SIZE AND IMPROVED MOISTURE
RESISTANCE

RECEIVED
OCT 22 2002
TECHNOLOGY CENTER 2800

Assistant Commissioner for Patents
Washington, D.C. 20231

AMENDMENT

Sir:

This is a response to the Office Action mailed July 16, 2002 in the above-identified application. Reconsideration of the application is respectfully requested.

FEE CALCULATION

Any additional fee required has been calculated as follows:

_____ If checked, "Small Entity" status is claimed.

	NO. CLAIMS AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR		EXTRA PRESENT		RATE		ADDIT. FEE
TOTAL	18	MINUS	20	* =	0	X	(\$9 SE or \$18)	\$	0.00
INDEP.	4	MINUS	3	** =	1	X	(\$42 SE or \$84)	\$	84.00
FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIM						X	(\$140 SE or \$280)	\$	0.00
TOTAL \$									84.00

* not less than 20

** not less than 3

If any additional payment is required, a check which includes the calculated fee of \$84.00 (OFGS Check No. 10994) is attached.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee during the prosecution of this application is not paid, the Patent Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

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